

Tests effectués à 100% sur les lots

tests	normes	equivalence AECQ	Chips
Capa - Df	CECC 32100 _ §4.6.1 (capa) _ §4.6.2 (DF)	-	100%
IR	CECC32100_§4.6.3		100%
Visual inspection (100%)	CECC 32100 - §4,5	AEC-Q200 method 9	100%
dpa	CECC 32100	AEC-Q200 method 5	50
Solderability	CECC 32100 §4,11		5
Resistance to soldering heat	CECC 32100 §4,10	AEC-Q200 method 15	5
Voltage proof	CECC 32100 - §4,6,4	-	10
Dimensions	CECC 32100 - §4,5	AEC-Q200 method 10	5

Tests de qualification périodiques

tests	normes	equivalence AECQ	Chips		Stacks	
			n	c	n	c
Capa - DF - IR (100%)	CECC 32100 _ §4.6.1 (capa) _ §4.6.2 (DF) _ §4.6.3 (IR)	-	50	0	25	0
Visual inspection (100%)	CECC 32100 - §4,5	AEC-Q200 method 9	50	0	25	0
dpa	CECC 32100	AEC-Q200 method 5	50	1	10	0
Voltage proof	CECC 32100 - §4,6,4	-	5	0	5	0
Dimensions	CECC 32100 - §4,5	AEC-Q200 method 10	5	0	5	0
Resistance to soldering heat	MIL STD 202 Method 210	AEC-Q200 method 15	5	0	5	0
Solderability	J-STD-202	AEC-Q200 method 18	5	0	5	0
Max capacitance change (-55°C / +125°C)	CECC 32100 - §4,7	-	Validé sur le lot céramique			
Life test (125°C - 1000h - 2Un)	MIL STD 202 M108 condition D	AEC-Q200 method 8	77	1	20	1
Humidity test (85°C - 85RH - 1000h)	MIL STD 202 M103	AEC-Q200 method 7	77	1	10	1
Bending	CECC 32100 §4,9	AEC-Q200 method 21	5	0	5	0
Plating thickness verification	CECC-IECQ (MIL grade)	-	5	0	2	0
High temperature exposure (125°C - 1000h - 0V)	MIL-STD-202 method 108	AEC-Q200 method 3	77	1	20	1
Terminal strength	MIL-STD-202 method 211	AEC-Q200 method 11	10	0	5	0
Adhesion	CECC 32100 - §4,8	-	10	0	5	0
Vibration	MIL-STD-202 method 204	AEC-Q200 method 14	24	0	10	0
Temperature cycling (-55°C / +125°C, 1000 cycles)	JESD22 Method-JA method 104	AEC-Q200 method 4	77	1	20	1